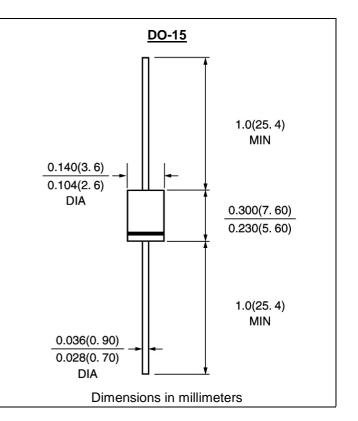
BYT52MGR

SINTERED GLASS JUNCTION FAST SWITCHING PLASTIC RECTIFIER VOLTAGE: 1000V CURRENT: 1.4A





High temperature metallurgic ally bonded construction Sintered glass cavity free junction Capability of meeting environmental standard of MIL-S-19500 High temperature soldering guaranteed 350°C /10sec/0.375"lead length at 5 lbs tension



MECHANICAL DATA

Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy Polarity: color band denotes cathode Mounting position: any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

	SYMBOL	BYT52MGR	units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	1000	V
Maximum RMS Voltage	V _{RMS}	700	V
Maximum DC blocking Voltage	V _{DC}	1000	V
Maximum Average Forward Rectified Current at I=10mm	I _{FAV}	1.4	A
Peak Forward Surge Current at Tp=10ms half sinewave	I _{FSM}	50.0	A
Maximum Forward Voltage at Forward Current 1.0A and 25°C	VF	1.30	V
Maximum DC Reverse CurrentTa = 25° Cat rated DC blocking voltageTa = 150° C	I _R	5.0 150	μA μA
Maximum Reverse Recovery Time (Note 1)	Trr	200	nS
Typical Thermal Resistance (Note 2)	Rth(ja)	100	K/W
Storage and Operating Junction Temperature	Tstg, Tj	-55 to +175	°C

Note:

1. Reverse Recovery Condition I_F=0.5A, I_R=1.0A, I_{RR}=0.25A

2. on P.C. board with spacing 20mm

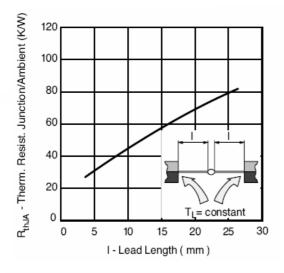


Figure 1. Max. Thermal Resistance vs. Lead Length

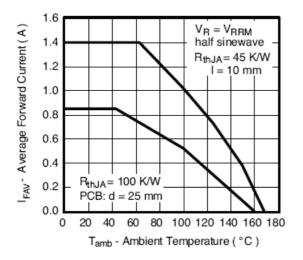


Figure 3. Max. Average Forward Current vs. Ambient Temperature

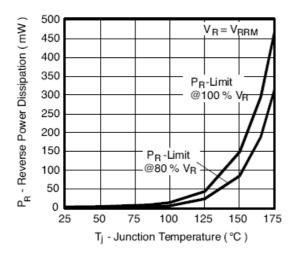


Figure 5. Max. Reverse Power Dissipation vs. Junction Temperature

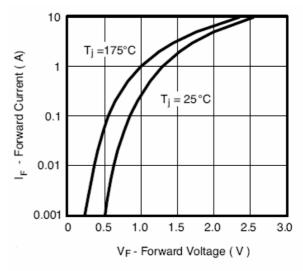


Figure 2. Forward Current vs. Forward Voltage

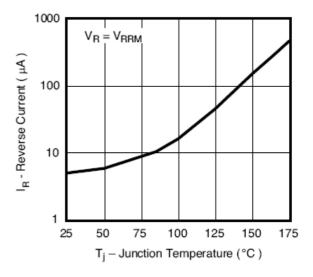


Figure 4. Reverse Current vs. Junction Temperature

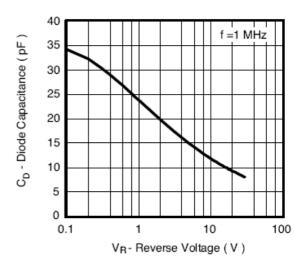


Figure 6. Diode Capacitance vs. Reverse Voltage

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